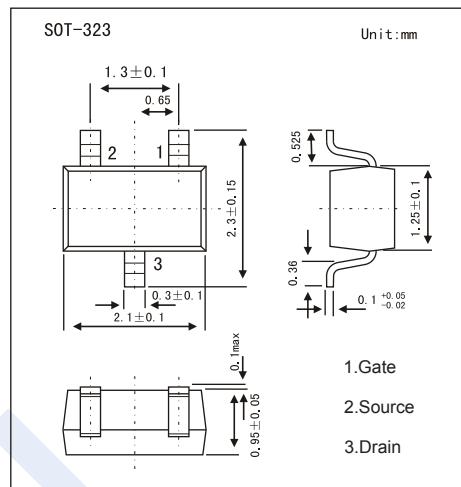
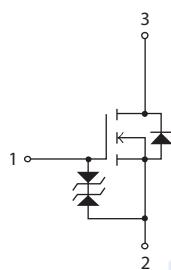


## N-Channel MOSFET

## 2KK5781

## ■ Features

- $V_{DS}$  (V) = 25 V
- $I_D$  = 0.75 A
- $R_{DS(ON)} < 350\text{m}\Omega$  ( $V_{GS} = 4.5\text{V}$ )
- $R_{DS(ON)} < 400\text{m}\Omega$  ( $V_{GS} = 2.7\text{V}$ )
- ESD Protection

■ Absolute Maximum Ratings ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	25	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current	$I_D$	0.75	A
		0.6	
Pulsed Drain Current ( $t_p=10\mu\text{s}$ )	$I_{DM}$	3	W
Power Dissipation (Note 1)	$P_D$	0.28	
Thermal Resistance.Junction- to-Ambient (Note 1)	$R_{\theta JA}$	450	$^\circ\text{C}/\text{W}$
Source Current (Body Diode) (Note 1)	$I_S$	0.3	A
ESD Rating – Machine Model	$V_{ESD}$	250	V
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to 150	

Note 1. Surface mounted on FR4 board using 1 in sq pad size. (Cu area = 1.127 in sq [1 oz] including traces).

## N-Channel MOSFET

## 2KK5781

■ Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	25			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$			0.5	$\mu\text{A}$
		$V_{DS}=20\text{V}, V_{GS}=0\text{V}, T_J = 70^\circ\text{C}$			2	
		$V_{DS}=20\text{V}, V_{GS}=0\text{V}, T_J = 125^\circ\text{C}$			5	
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			$\pm 3$	
<b>ON CHARACTERISTICS (Note 2)</b>						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	0.65		1.5	V
Static Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS}=4.5\text{V}, I_D=0.6\text{A}$			350	$\text{m}\Omega$
		$V_{GS}=2.7\text{V}, I_D=0.2\text{A}$			400	
Forward Transconductance	$g_{FS}$	$V_{DS}=5\text{V}, I_D=0.5\text{A}$		0.5		S
<b>CHARGES AND CAPACITANCES</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$		49	60	$\text{pF}$
Output Capacitance	$C_{oss}$			22.4		
Reverse Transfer Capacitance	$C_{rss}$			8		
Total Gate Charge	$Q_g$	$V_{GS}=4.5\text{V}, V_{DS}=15\text{V}, I_D=0.8\text{A}$		1.2	1.5	$\text{nC}$
Gate Source Charge	$Q_{gs}$			0.28		
Gate Drain Charge	$Q_{gd}$			0.3		
<b>SWITCHING CHARACTERISTICS (Note 3)</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 4.5 \text{ V}, V_{DS} = 15 \text{ V}, I_D = 0.7 \text{ A}, R_G = 51 \Omega$		5		$\text{ns}$
Turn-On Rise Time	$t_r$			8.2		
Turn-Off Delay Time	$t_{d(off)}$			23		
Turn-Off Fall Time	$t_f$			41		
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode Forward Voltage	$V_{SD}$	$I_S=0.6\text{A}, V_{GS}=0\text{V}$		0.82	1.2	V

Notes:

2. Pulse Test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Switching characteristics are independent of operating junction temperatures.

## ■ Marking

Marking	KDC
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**N-Channel MOSFET****2KK5781**

## ■ Typical Characteristics

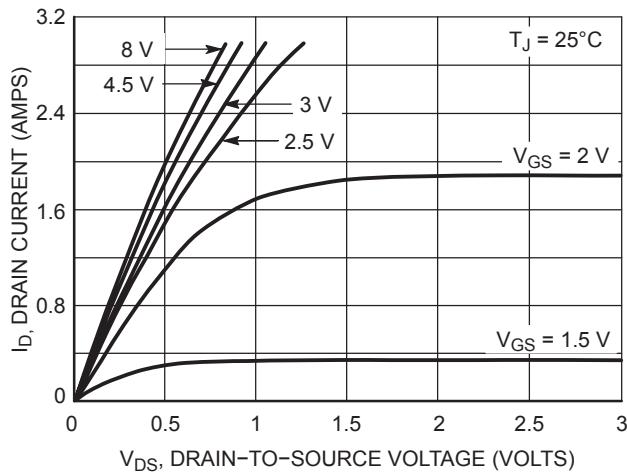


Figure 1. On-Region Characteristics

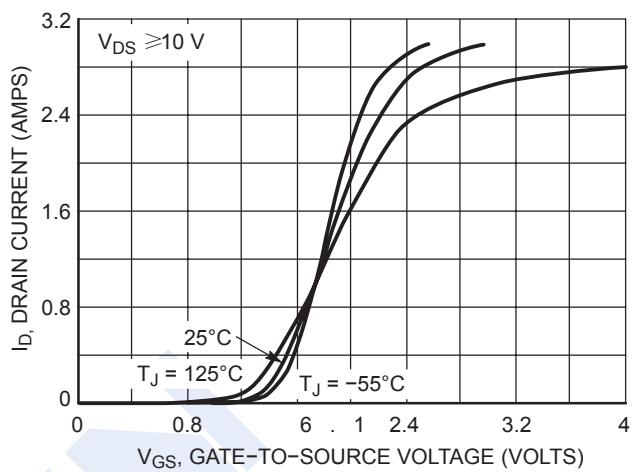


Figure 2. Transfer Characteristics

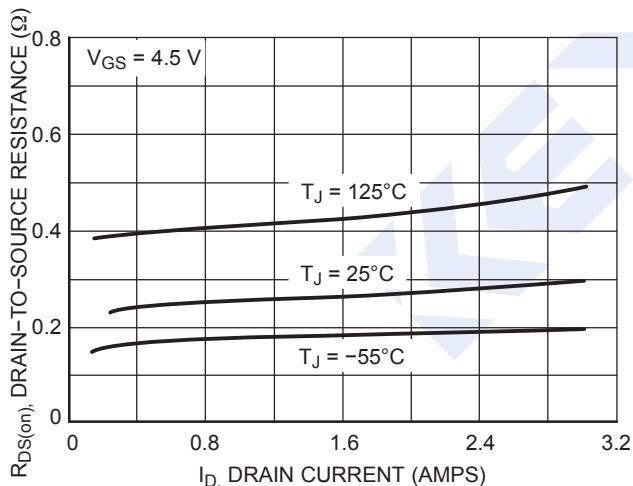


Figure 3. On-Resistance vs. Drain Current and Temperature

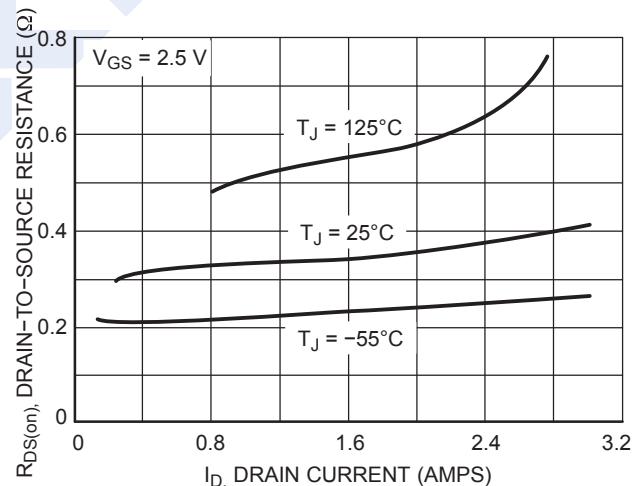


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

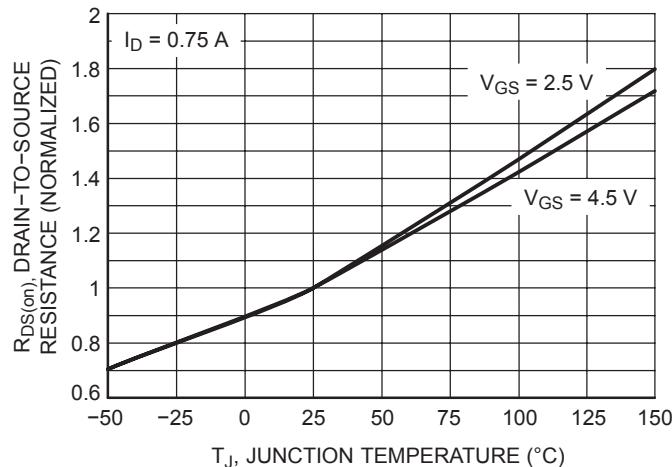
**N-Channel MOSFET****2KK5781**

Figure 5. On-Resistance Variation with Temperature

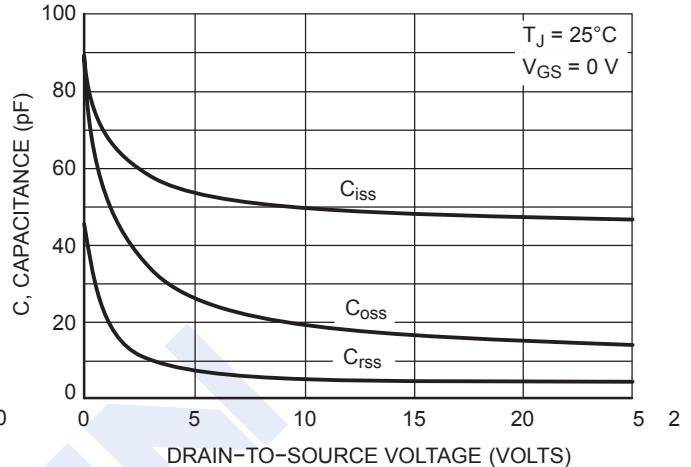


Figure 6. Capacitance Variation

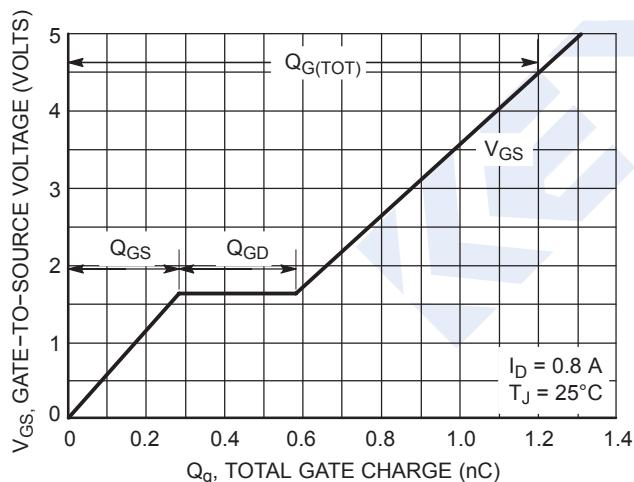


Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

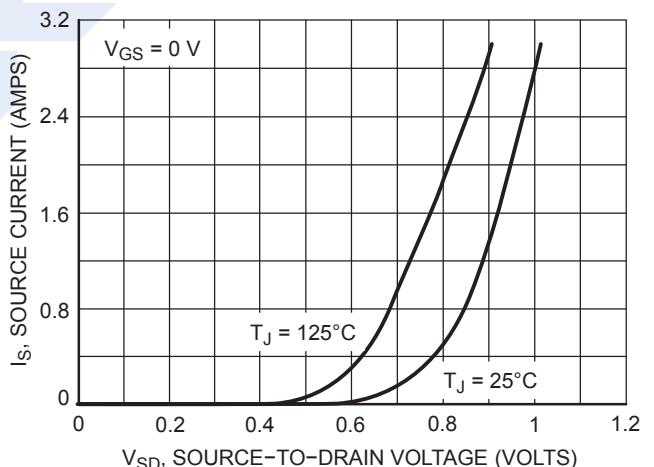


Figure 8. Diode Forward Voltage vs. Current